

KIOXIA Spotlights Flash Solutions Shaping the Future of Storage at FMS 2024

Pioneering 2Tb QLC Flash Memory and RAID Offload Technology Among KIOXIA Solutions Driving Storage Advancements Across Diverse Market Segments

SAN JOSE, Calif., August 5, 2024 – [KIOXIA](#) will be at [FMS: the Future of Memory and Storage](#) this week to highlight how its breakthrough flash memory solutions are driving advancements and improvements in hundreds of applications across a wide range of market segments – from AI, IoT, and automotive to data centers, the cloud and the edge. Key highlights will include the industry’s highest capacity¹ 2Tb QLC flash memory featuring the latest BiCS FLASH™ 3D flash memory as well as NVMe™ SSDs enabling AI workloads and KIOXIA RAID Offload technology.

KIOXIA invented flash memory more than 35 years ago, and is committed to making memory solutions that enable the applications of tomorrow. Prior to the show this week, KIOXIA was recognized by FMS with the Lifetime Achievement Award for 2024. The company’s engineering team was honored with this prestigious award for its pioneering work creating and commercializing 3D flash memory – a breakthrough technology that has become fundamental to every flash memory-based product today. The award presentation will take place on Tuesday, Aug 6th at 11:30am as part of the opening keynotes.

"Flash storage solutions from KIOXIA are at the heart of countless applications, driving innovation across a diverse array of industries," said Scott Nelson, executive vice president and chief marketing officer for KIOXIA America, Inc. "Our advanced memory solutions are integral to the functionality and advancement of modern technology. Whether you're looking to upgrade, create, or innovate, you can make it with KIOXIA. We unlock new possibilities and turn visions into realities."

At FMS, KIOXIA will give a keynote presentation and several educational sessions covering a range of topics:

FMS Keynote Presentation:

“Memory Innovations Fueling the New Currency of Our Digital World”

Tuesday, August 6 at 11 a.m. PDT

Atsushi Inoue, vice president and technology executive for KIOXIA Corporation’s Memory Division, and Neville Ichhaporia, senior vice president and general manager of the SSD business unit for KIOXIA America, Inc. will present this keynote session.

Executive AI Premier Level Panel:

“Storage and Memory Innovation for AI Workloads”

Thursday, August 8 at 11 a.m. PDT

Rory Bolt, senior fellow and principal architect, SSD Business Unit for KIOXIA America Inc., will participate in an executive session, hosted and moderated by NVIDIA, that assembles a panel of experts from across the storage and memory industry to provide insights into solutions for different AI applications.

Special AI Panel:

“Emerging Technologies for AI Chip and Generative AI Optimization”

Thursday, August 8 at 1:30 p.m. PDT

Led by an industry analyst, Rory Bolt will join other invited speakers from influential processor, memory and generative AI companies to discuss the hardware and software technologies driving the future of AI chips and generative AI customer implementations.

Educational Sessions by KIOXIA:

SSD Technology Track

Tuesday, 8/6, 9:45-10:50am

SSDT-102-1: SSD Technologies for Compute Use Cases

Speaker: Devesh Rai

- Review of RAID Offload Concept

Tuesday, 8/6, 9:45-10:50am

SSDT-102-1: SSD Technologies for Compute Use Cases

Speaker: Nick Snow

- PCIe® 6.0 SSDs: Powering the Future of Compute and Storage

Thursday, 8/8, 1:25-2:30pm

SSDT-304-1: New Form Factors and Interfaces for SSDs

Speaker: Ilya Cherkasov

- New Form Factors and Interfaces for SSDs

Flash Architectures Track

Tuesday, 8/6, 8:30-9:45am

FARP-101-1: FDP and ZNS

Speaker: Rory Bolt

- Flexible Data Placement (FDP): What Every Storage Architect Should Know

Sustainability Track

Wednesday, 8/7, 9:45-10:50am

SUST-202-1: Sustainable Data Centers and Energy Efficiency

Speaker: Satvik Vyas

- Achieve Significant Reduction in Data Movement by Offloading Data Scrubbing

CXL[®] Track

Thursday, 8/8, 8:30-9:35am

CXLT-301-1:

Speaker: Mahinder Saluja

- TCO Use Cases for CXL Attached Flash Memory

Networks and Connections Track

Thursday, 8/8, 9:45-10:50am

NETC-302-1: NVMe over Fabrics[®] Is Everywhere

Speaker: Mahinder Saluja

- Redefining Data Redundancy with RAID Offload

AI/ML Track

Wednesday, 8/7, 3:10-4:15pm

AIML-203-1: Generative AI

Speaker: Assaf Sella

- Flash is Driving Scale in RAG-based LLMs

SuperWomen in Flash Track

Wednesday, 8/7, 4:00-6:15pm

Evolution Courtyard, Floor 1

Speaker: Jenna Fong

- Celebrating the success of women in the industry

KIOXIA Booth Demos

Product and technology demonstrations will be given in the iconic 2-level KIOXIA booth #307 - featuring eight separate exhibit locations - on the show floor including:

- **Next Generation KIOXIA BiCS FLASH™ 3D Flash Memory:** Display showing CMOS Bonded Array (CBA) architecture and a lateral density model.
- **KIOXIA CM7 Series E3.S Enterprise NVMe SSDs:** Live demo running a BaM workload and highlighting the EDSFF form factor.
- **KIOXIA Optical NVMe SSD Technology:** Featuring CM7 Series Enterprise NVMe SSDs.
- **KIOXIA CD8P Series Data Center SSDs:** Live demo running AiSAQ ANN search for AI.
- **KIOXIA CXL Solutions:** Featuring BiCS FLASH™ 3D flash memory and XL-FLASH high-bandwidth, low-latency CXL solutions.
- **KIOXIA RAID Offload Technology:** Move RAID functionality to SSDs.
- **KIOXIA Automotive UFS:** Driving the future of automotive applications.
- **KIOXIA XD7P Series E1.S Data Center SSDs:** Demo of Live Migration.

For more information, please visit www.kioxia.com, and follow the company on [X](#), [formerly known as Twitter](#) and [LinkedIn®](#).

About KIOXIA America, Inc.

[KIOXIA America, Inc.](#) is the U.S.-based subsidiary of [KIOXIA Corporation](#), a leading worldwide supplier of flash memory and solid-state drives (SSDs). From the invention of flash memory to today's breakthrough BiCS FLASH™ 3D technology, KIOXIA continues to pioneer innovative memory, SSD and software solutions that enrich people's lives and expand society's horizons. The company's innovative 3D flash memory technology, BiCS FLASH, is shaping the future of storage in high-density applications, including advanced smartphones, PCs, SSDs, automotive, and data centers. For more information, please visit KIOXIA.com.

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application information contained here is subject to the most recent applicable KIOXIA product specifications.

Notes:

1: Source: As of July 3, 2024. KIOXIA survey.

In every mention of a KIOXIA product: Product density is identified based on the density of memory chip(s) within the Product, not the amount of memory capacity available for data storage by the end user. Consumer-usable capacity will be less due to overhead data areas, formatting, bad blocks, and other constraints, and may also vary based on the host device and application. For details, please refer to applicable product specifications. The definition of 1KB = 2^{10} bytes = 1,024 bytes. The definition of 1Gb = 2^{30} bits = 1,073,741,824 bits. The definition of 1GB = 2^{30} bytes = 1,073,741,824 bytes. 1Tb = 2^{40} bits = 1,099,511,627,776 bits.

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